PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company		STMicroelectronics International N.V
1.2 PCN No.		MDG/17/9820
1.3 Title of PCN		Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for products in UFQFPN 4x4 package
1.4 Product Category		UFQFPN 4x4 COL packaged products
1.5 Issue date		2017-02-17

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	ROBERTSON HEATHER	
2.1.2 Phone	+1 8475853058	
2.1.3 Email	heather.robertson@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Michel BUFFA	
2.1.2 Marketing Manager	Daniel COLONNA	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change			
3.1 Category	3.2 Type of change	3.3 Manufacturing Location	
Materials		Stats ChipPAC Shanghai China (SCC), Stats ChipPAC Jiangyin China (JSCC)	

4. Description of change		
	Old	New
4.1 Description	Current location: Stats ChipPAC Shanghai China (SCC)	Transfer from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) location. See more information on PCN 9820 – Additional information document attached.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Change lead shape: with neck design. See in PCN 9820 – Additional information document attached. No change in fit, function, reliability or process ability.	

5. Reason / motivation for change		
	Due to Shanghai China site closure, production is relocated to Jiangyin China site. This Product Change Notification (PCN) concerns only UFQFPN 4x4 COL packaged products.	
5.2 Customer Benefit	SERVICE CONTINUITY	

6. Marking of parts / traceability of change		
6.1 Description	Traceability is described in PCN 9820_Additional information attached document.	

7. Timing / schedule		
7.1 Date of qualification results	2017-06-02	
7.2 Intended start of delivery	2017-07-02	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
8.1 Description 9820 PCN9820_RERMCD1623- UQFN4x4 COL JSCC- MCD QA reliability plan.pdf			df
8.2 Qualification report and qualification results Available (see attachment) Issue Date 2017-02-17		2017-02-17	

9. Attachments (additional documentations)

9820 Public product.pdf 9820 PCN9820_Additional information.pdf 9820 PCN9820_RERMCD1623- UQFN4x4 COL JSCC- MCD QA reliability plan.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F031G4U6	
	STM32F031G6U6	
	STM8L151G3U6	
	STM8L151G4U6	
	STM8L151G6U6	
	STM8L101G2U6	
	STM8L101G2U6A	
	STM8L101G3U6	
	STM8L101G3U6A	



Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title: Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for

products in UFQFPN 4x4 package **PCN Reference**: MDG/17/9820

Subject: Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32L031G6U7STR	STM8TL53G4U6	STM32F031G6U6TR
STM8L101G3U6TR	STM32F031G4U7TR	STM32F031G6U7TR
STM32F031G4U6TR	STM8L151G6U7	STM8L151G6U3TR
STM32L031G6U6	STM32F038G6U6	STM8L151G6U6TR
STM8TL52G4U6	STM32F031G6U6	STM8L101G2U6A
STM32F031G4U6	STM32F031G4U7	STM32F048G6U6
STM8TL53G4U6TR	STM8L151G6U6	STM32L021G4U6
STM32F031G6U7	STM32L031G4U6	STM32L031G6U6TR
STM32F042G6U6	STM8L151G3U6	STM8L151G4U6
STM32L011G3U7	STM8L151G2U6	STM32L011G3U6
STM32L041G6U7	STM8L151G4U6TR	STM8L151G6U3
STM8L101G3U6	STM8L151G3U6TR	STM8L101G3U6A
STM8L151G3U3	STM32L011G4U6TR	STM32L031G6U7
STM32L011G4U6	STM32F042G4U6	STM8L151G4U3
STM8L101G2U6TR	STM8L101G2U6	STM8L151G6U7TR
STM32F042G4U6TR		

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